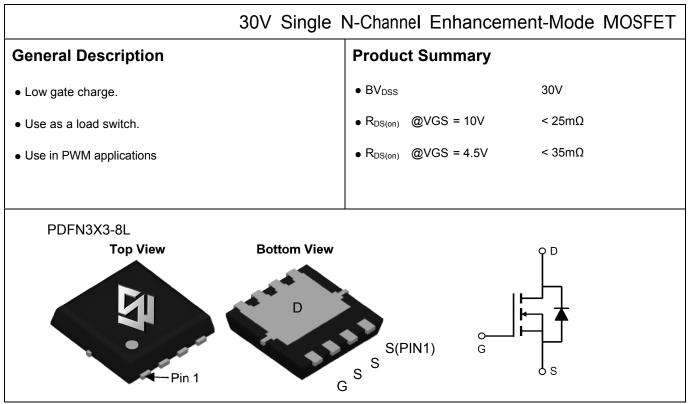


SWD7408



Parameter	Symbol	Maximum	Units
Drain-Source Voltage	V _{DS}	30	V
Gate-Source Voltage	V _{GS}	±20	V
Drain Current (T _A =25°C)		6.0	А
Drain Current (T _A =75°C)	l _D	4.8	А
Pulsed Drain Current ^a	I _{DM}	30	А
Power Dissipation ^b (T _A =25°C)		2.0	W
Power Dissipation ^b (T _A =75°C)	P _D	1.4	W
Junction and Storage Temperature Range	T _{J,} T _{STG}	-55 ~ +150	°C

Thermal Characteristics					
Parameter	Symbol	Maximum	Units		
Junction-to-Ambient ^a (t \leq 10s)	5	50	°C/W		
Junction-to-Ambient ^{a,d} (Steady-State)	R _{eja}	90	°C/W		
Junction-to-Lead (Steady-State)	R _{eJL}	25	°C/W		



SWD7408

Symbol	Parameter	Conditions	Min	Тур	Мах	Units
Off Char	acteristics					
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS} = 0V , I _D = 250uA	30			V
I _{DSS}	Zero Gate Voltage Drain Current	V_{DS} = 30V , V_{GS} = 0V			1	uA
I _{GSS}	Gate-Body Leakage Current	V_{GS} = ±20V, V_{DS} = 0V			±100	nA
On Char	acteristics					
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS} = V_{GS} , I_D = 250 uA	1		2.5	V
R _{DS(ON))}	Drain-Source On-State Resistance	V_{GS} = 10V , I_D = 6.0A		20	25	mΩ
		V_{GS} = 4.5V , I _D = 5.0A		25	35	mΩ
g fs	Forward Transconductance	V_{DS} = 5.0V , I_D = 6.0A		20		S
Drain-So	ource Diode Characteristics					
V_{SD}	Diode Forward Voltage	V_{GS} = 0V , I _S = 1.0A			1.1	V
ls	Maximum Body-Diode Continuous Current				2.5	А
Dynamic	Characteristics					
C _{iss}	Input Capacitance			802		pF
C _{oss}	Output Capacitance	V _{DS} = 15V , V _{GS} = 0V f = 1.0MHz		105		pF
C _{rss}	Reverse Transfer Capacitance			85		pF
Switchin	g Characteristics					
Qg	Total Gate Charge			12.8		nC
Q_{gs}	Gate-Source Charge	V _{DS} = 15V , I _D = 6.0A V _{GS} = 10V		4.5		nC
Q_{gd}	Gate-Drain Charge			3.8		nC
t _{D(ON})	Turn-On Delay Time	V _{DD} = 15V , ID = 1A V _{GS} = 10 V R _{GEN} = 30hm		6.2		ns
tr	Turn-On Rise Time			4.8		ns
$t_{D(OFF)}$	Turn-Off Delay Time			14.5		ns
t _f	Turn-Off Fall Time			3.5		ns

a. Repetitive rating, Pulse width limited by junction temperature T_{J(MAX)}=150 °C. Ratings are based on low frequency and duty cycles to keep initial T_J=25 °C

b. The power dissipation P_D is based on $T_{J(MAX)}\text{=}150~^{o}\text{C}$, using ${\leqslant}10\text{s}$ junction-to-ambient thermal resistance.

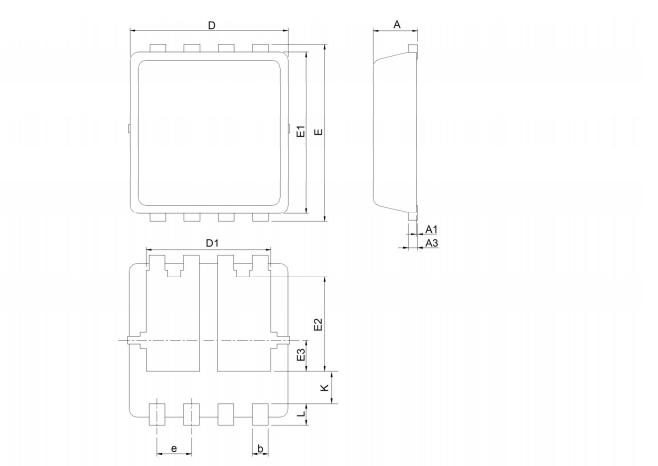
c. The value of $R_{\theta JA}$ is measured with the device mounted on $1in^2$ FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^{\circ}$ C. The value in any given application depends on the user's specific board design.

d. The $R_{\theta JA}$ is the sum of the thermal impedence from junction to lead $R_{\theta JL}$ and lead to ambient.



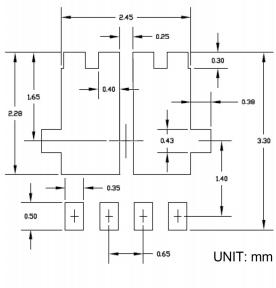


PDFN3x3-8L Package



Ş		DFN	3x3-8	
SY MBO	MILLIM	MILLIMETERS		IES
6 L	MIN.	MAX.	MIN.	MAX.
A	0.80	1.00	0.031	0.039
A1	0.00	0.05	0.000	0.002
A3	0.10	0.25	0.004	0.010
b	0.24	0.35	0.009	0.014
D	2.90	3.10	0.114	0.122
D1	2.25	2.45	0.089	0.096
E	3.10	3.30	0.122	0.130
E1	2.90	3.10	0.114	0.122
E2	1.65	1.85	0.065	0.073
E3	0.56	0.58	0.022	0.023
е	0.65 BSC		0.026	BSC
к	0.475	0.775	0.019	0.031
L	0.30	0.50	0.012	0.020





单击下面可查看定价,库存,交付和生命周期等信息

>>SiliconWisdom(矽睿半导体)